

ABSTRACT OF THE DISCLOSURE

Semiconductor devices, semiconductor wafers, and
 semiconductor modules are provided wherein the
 semiconductor device has a small warp; damages at chip edge
 and cracks ^{occurring} in a dropping test are scarcely generated; and
 the semiconductor device is superior in mounting
 reliability and mass producibility. *The semiconductor includes a*
~~The semiconductor device 17 comprising a~~
 semiconductor chip 64; a porous stress relaxing layer 3
 provided on the plane, whereon circuits and electrodes are
 formed, of the semiconductor chip; a circuit layer 2
 provided on the stress relaxing layer and connected to the
 electrodes; and external terminals 10 provided on the
 circuit layer; wherein an organic protecting film 7 is
 formed on the plane, opposite to the stress relaxing layer,
 of the semiconductor chip, and respective side planes of
 the stress relaxing layer, the semiconductor chip 6, and
 the protecting film 7 are exposed outside on ^{the} a same plane.

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